

31

Part No. 3565B97W0 3300100-10





目录

电性参数

典型特性曲线

可靠性实验

外形尺寸

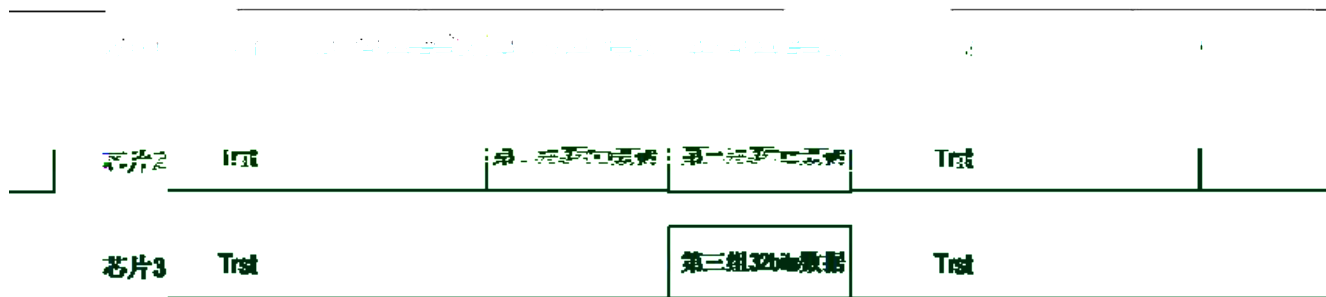
包装

焊接指导

使用注意事项







1 MCU 2 3

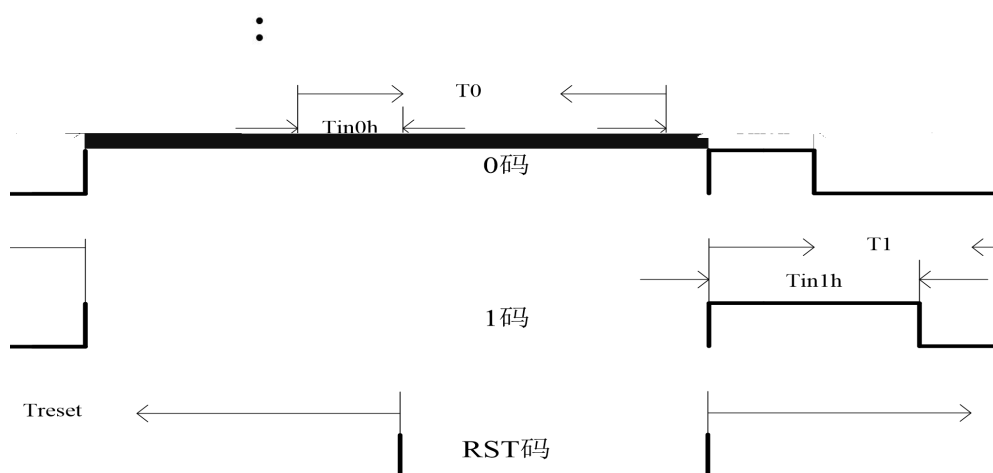
Note: D1 refers to the data sent by MCU, and D2, D3 and D4 refer to the data automatically shaped and forwarded by cascade circuit

32bit



GRBW

Note: high order first send, send data in the order of GrB











Packaging (2)

[illegible]

焊接指导 (1)

Guideline for Solder

使用烙铁

30

Z Pa °Wü ð

a

VJ 7a G

OMQa F+Ð P

VEÖB •ÖÖP• aÖÖÖMÖ• p

E

RO

PE



O

a2\$

L @ sù U €Ð ... 2\$ H€BA`• ð

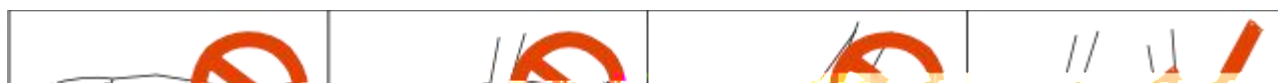




使用注意事项（3）

Precautions (3)

其他事项



眼睛保护忠告

